

ENGINEERING
TOMORROW'S
PRODUCTION



RDL (Redistribution Layer) Process

Wet Chemical Equipment
for Semiconductor Panel Level Packaging

Technical Specifications

Developing Equipment

Materials	PI / PR / Dry film
Chemicals	TMAH / Solvent / Alkaline
Uniformity	>90 % (Base on customer request)

Etching Equipment

Application	Ti / Cu seed layer
Uniformity	>90 % (Base on customer request)

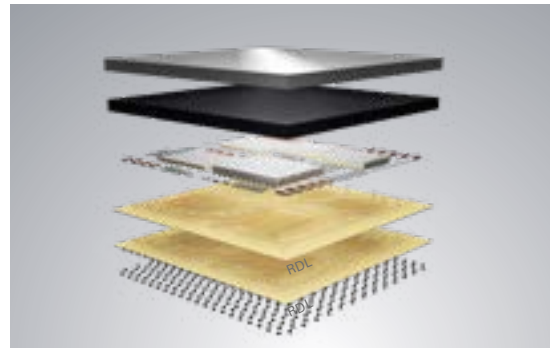
Stripping Equipment

Materials	PR for wet film and dry film
Chemicals	Solvent / Alkaline
Uniformity	No residue

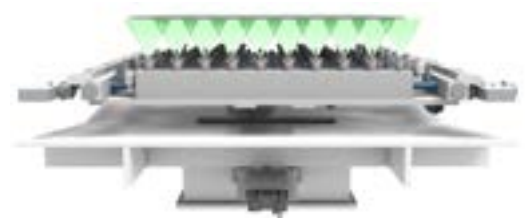
Surface Treatment Equipment

Application	Micro etching & acid rinse for substrate roughness
Uniformity	>90 % (Base on customer request)

*Specific performance parameters depend on the application.



RDL enables multi-die integrated packaging with finer line/spacing for higher functionality and reliability.



Switchable independent chemical and water drainage paths.

→ Features

- **Modular & Compact Design**
Integrated automation for etcher, stripper, and developer.
- **Proven RDL Performance**
Trusted by Tier 1 PLP manufacturers for quality, scalability & success.
- **Fine Line Capability**
Optimized for lithography tools to achieve high-resolution patterns.
- **Comprehensive Wet Functions**
Covers acid rinse, micro-etch, develop, pre-dip, package bond, Ti/Cu etch, and stripping.
- **Smart CMS Integration**
Inline chemical monitoring with automatic dosing for stable process control.

